

CLAIMS:

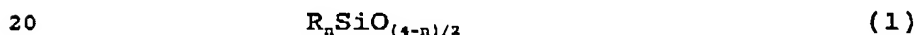
1. A silicone resin composition for LED devices, comprising

- 5 (A) a silicone resin having at least two alkenyl groups bonded to silicon atoms in a molecule,
(B) an organohydrogensilane and/or organohydrogenpolysiloxane having at least two hydrogen atoms bonded to silicon atoms in a molecule, and
10 (C) an addition reaction catalyst.

2. The composition of claim 1 which is heat curable.

3. A silicone resin composition for LED devices, comprising

15 (A) 100 parts by weight of a liquid or solid organopolysiloxane represented by the average compositional formula (1):



wherein R is independently a substituted or unsubstituted monovalent hydrocarbon group, alkoxy group or hydroxyl group, 0.1 to 80 mol% of the entire R groups being alkenyl groups,
25 and n is a positive number of $1 \leq n < 2$, and having a viscosity of at least 10 mPa·s at 25°C,

(B) 2 to 100 parts by weight of an organohydrogenpolysiloxane having at least two SiH bonds in a molecule represented by the average compositional formula
30 (2):

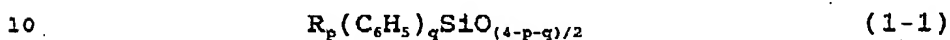


wherein R' is independently a substituted or unsubstituted
35 monovalent hydrocarbon group excluding an aliphatic unsaturated hydrocarbon group, "a" is a positive number of 0.7 to 2.1, "b" is a positive number of 0.001 to 1.0, satisfying $0.8 \leq a+b \leq 2.6$, and having a viscosity of up to 1,000 mPa·s at 25°C and/or an organohydrogensilane

represented by the formula: $R'_c\text{SiH}_{(4-c)}$ wherein R' is as defined above and c is 1 or 2, and

(C) a catalytic amount of an addition reaction catalyst.

4. The composition of claim 3 wherein component (A) is a liquid or solid organopolysiloxane represented by the average compositional formula (1-1):



wherein R is independently a substituted or unsubstituted monovalent hydrocarbon group, alkoxy group or hydroxyl group, 0.1 to 80 mol% of the entire R groups being alkenyl groups, 15 and p and q are positive numbers satisfying $1 \leq p+q < 2$ and $0.20 \leq q/(p+q) \leq 0.95$, and having a viscosity of at least 100 mPa·s at 25°C.

5. The composition of claim 3 wherein component (B) is an organohydrogenpolysiloxane of the compositional formula (2) 20 wherein phenyl groups comprise at least 5 mol% of the entire R' and H .

6. The composition of claim 3 wherein component (B) is a 25 mixture of an organohydrogenpolysiloxane of the compositional formula (2) wherein phenyl groups comprise less than 15 mol% of the entire R' and H and an organohydrogenpolysiloxane of the compositional formula (2) wherein phenyl groups comprise at least 15 mol% of the entire R' and H in a weight ratio 30 between 1:9 and 9:1.